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ABSTRACT

**TITLE OF INVENTION: RESIN SEALING DIE, RESIN-SEALED-TYPE
SEMICONDUCTOR DEVICE AND METHOD OF
MANUFACTURING THE DEVICE**

The present invention intends to improve the productivity and reliability of a resin-sealed-type semiconductor device. Therefore, the invention provides a resin sealing die for integrally molding a semiconductor chip, a lead frame to which the semiconductor chip is fixed, and metal wires which electrically connect the electrode terminals of the semiconductor chip to the inner leads of a head frame with sealing resin to manufacture a resin-sealed-type semiconductor device, wherein a cavity of the resin sealing die is formed at a portion where separable upper and lower dies confront each other, at least one of the upper surface of the cavity of the upper die and the lower surface of the cavity of the lower die comprises an engraved hole, and a metal block having a mark carved on a reference surface thereof facing the cavity is detachably attached to the engraved hole. The mark is imprinted on the surface of the resin-sealed-type semiconductor device concurrently with the resin molding, thereby realizing a relief marking.

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